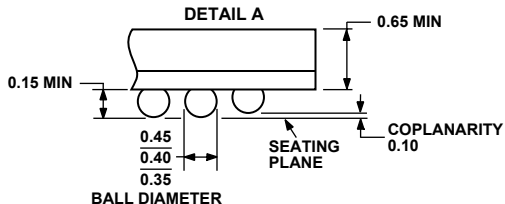
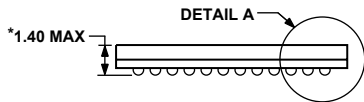
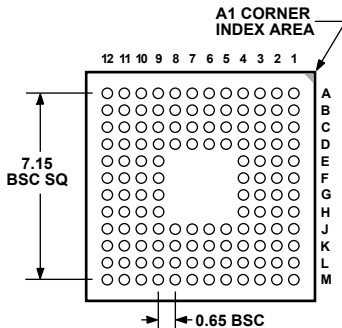
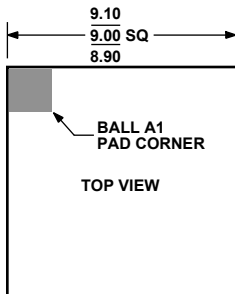


128-Lead Chip Scale Package Ball Grid Array [CSP_BGA]

(BC-128)

Dimensions shown in millimeters



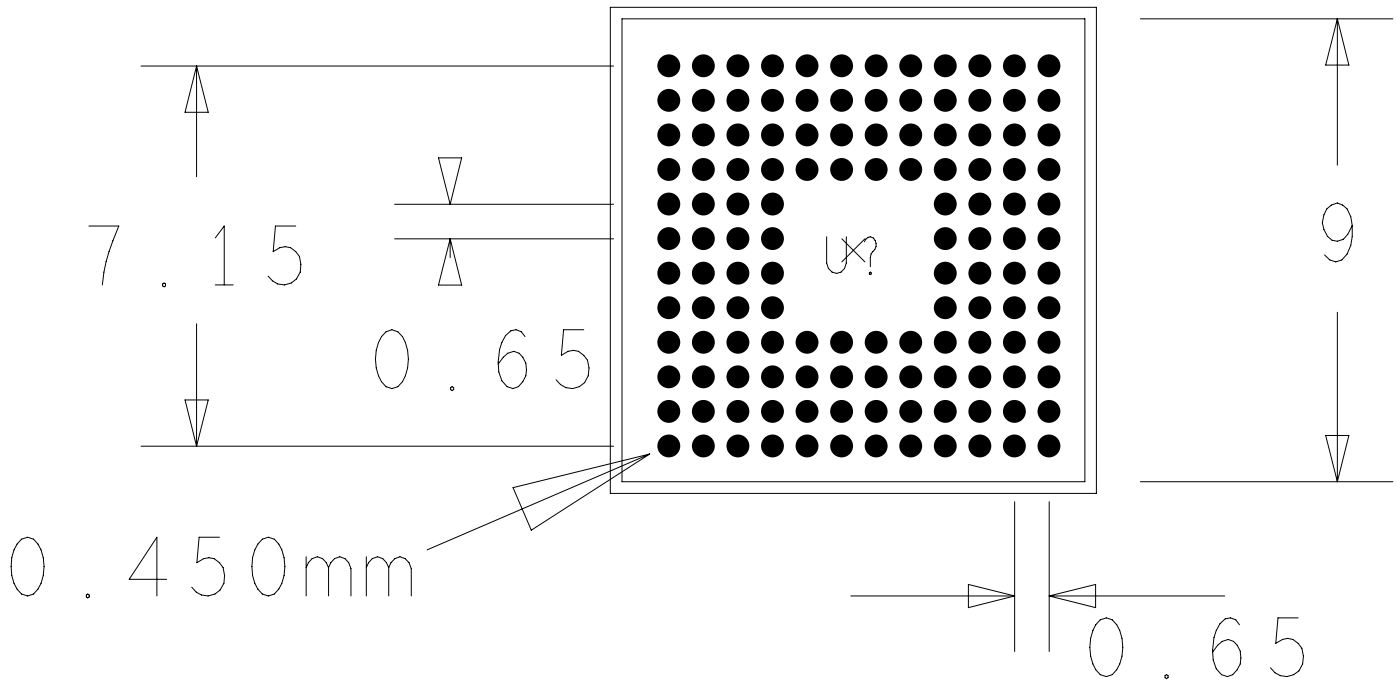
*COMPLIANT TO JEDEC STANDARDS MO-225
WITH THE EXCEPTION OF PACKAGE HEIGHT.

Analog Devices

BC - 128 - 1

REV A

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(Dim. are in MM)

LAST MODIFIED 08/03/07